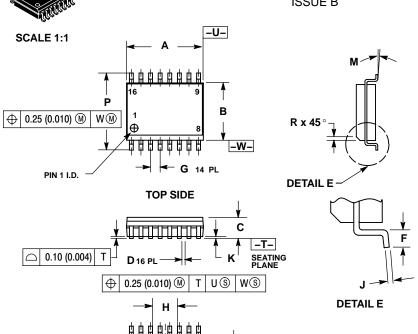
EXPOSED PAD

SOIC 16 LEAD WIDE BODY, EXPOSED PAD

CASE 751R-02 **ISSUE B**

DATE 18 JUL 2005



10.15 10.45 0.400 0.411 Α В 7.40 7.60 0.292 0.299 2.35 2.65 0.093 0.104 D 0.49 0.014 0.019 0.35 0.50 0.90 0.020 0.035 1.27 BSC 0.050 BSC 0.130 0.138 3.31 3.51 0.130 0.138 0.25 0.32 0.010 0.012 Н 0.10 0.25 0.004 0.009 4.58 4.78 0.180 0.188 0 ° 0 9 10.05 10.55 0.395 0.415

- 1. DIMENSIONING AND TOLERANCING PER ANSI

DIM

- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD
- PROTRUSION MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF THE D
- DIMENSION AT MAXIMUM MATERIAL CONDITION.

 6. 751R-01 OBSOLETE, NEW STANDARD 751R-02.

INCHES

MIN MAX

MILLIMETERS

MIN MAX

MARKING DIAGRAM

R 0.25 0.75 0.010 0.029

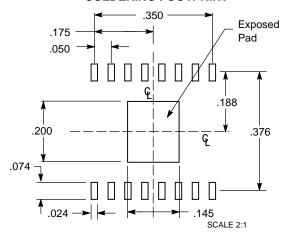


XXX = Specific Device Code = Assembly Location Α

= Wafer Lot WL ΥY = Year WW = Work Week

SOLDERING FOOTPRINT*

BACK SIDE



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		"CONTROLLED COPY" in red.	
DESCRIPTION:	SOIC-16, WB EXPOSED PAD		PAGE 1 OF 2



DOCUMENT	NUMBER:
98AON10370)D

PAGE 2 OF 2

		1
ISSUE	REVISION	DATE
В	ADDED SOLDERING FOOTPRINT. REQ. BY F. KOLANKO. FIXED EXPOSED PAD AND CHANGED DIM H. REQ. BY P. CELAYA.	18 JUL 2005

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